Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1608-02** DATE: **6-Sep-2016**

Product Affected: 4DB0226KA3ZAVG(8)
(built in FCCSP-53)

Date Effective: **6-Dec-2016**

MEANS OF DISTINGUISHING CHANGED DEVICES:

☐ Product Mark
■ Back Mark
☐ Date Code
☐ Other

Lot # will have:
"SL" prefix for SFA, Korea

Contact: IDT PCN DESK

Attachment: ■ Yes ☐ No

E-mail: pcndesk@idt.com

Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
■ Manufacturing Site
☐ Data Sheet
☐ Other

This notification is to advise our customers that IDT is adding SFA Semicon Co. Ltd, Korea (previously named as STS Semiconductor & Telecommunication Co. Ltd) as an alternate assembly facility for parts that are currently assembled at ASEK and ASECL, Taiwan.

There is no change to the moisture performance.

Attachment I details the qualification results.

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1608-02

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding SFA Semicon Co. Ltd, Korea (previously named as STS Semiconductor & Telecommunication Co. Ltd) as an alternate assembly facility for parts that are currently assembled at ASEK and ASECL, Taiwan.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (ASE Kaohsiung, Taiwan & ASE Chungli, Taiwan)	**Alternate Assembly (SFA, Korea)**
Die Bump	Sn1.8Ag	Sn1.8Ag
Mold Compound	KE-G1250FC-20B	Panasonic CV8710U
Substrate	ABF-GX13/E700GR core	ABF-GX13/E700GR core
Solder Balls	Sn98.25/Ag1.2/Cu0.50/Ni0.05	Sn98.25/Ag1.2/Cu0.50/Ni0.05

ATTACHMENT I - PCN # : A1608-02

Qualification Information and Qualification Data:

Affected Packages: FCCSP-53

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: FCCSP-53

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test